

Bill of Materials

	SCM	SCC	Remarks
Die Attach	Hitachi EN4900	Hitachi EN4900	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Hitachi CEL9220	Hitachi CEL9220	
Lead Finish	NiPdAu	NiPdAu	



Reliability Qualification Plan for LFCSP Package in NiPdAu Pre-plated Leadframe at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	April 2014
Low Temperature Storage (LTS)	JEDEC <i>JESD22-A119</i>	3 x 77	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	April 2014

*Preconditioned per JEDEC/IPC J-STD-020